

ABSTRACT OF THE DISCLOSURE

According to one aspect of the invention, a method and apparatus for handling semiconductor packages is provided. The semiconductor packages include package substrates with a plurality contact formations on a bottom surface thereof. The packages are fed into a handling machine, which includes a CCD camera. The contact formations are imaged by the CDD camera after the semiconductor packages are picked from the feeder. The captured image is relatively low resolution and is made of relatively large pixels. A computer approximates a center of the contact formations based on the captured images and places the packages on a circuit board in the handling machine.